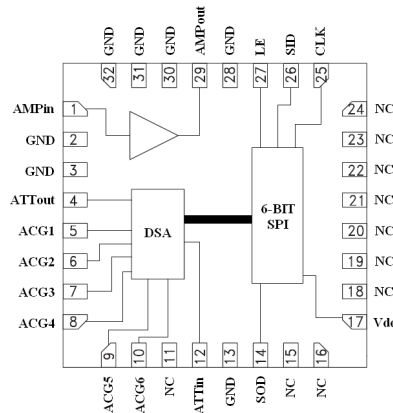


TQM8M9075

0.05-4 GHz Digital Variable Gain Amplifier

Pin Description



Pin #	Symbol	Description
1	Ampin	Amp RF input
2, 3, 13, 28, 30, 31, 32	GND (Ground)	DC ground
11, 15, 16, 18-24	NC (No Connect)	No electrical connection. Provide land pads for PCB mounting integrity.
29	Ampout	Amp RF output / DC supply
12	ATTin	DSA Input
4	ATTout	DSA Output
5, 6, 7, 8, 9, 10	ACG1-6	Place external capacitor to Ground for applications below 700 MHz.
14	SOD	Serial Data Out
17	Vdd	DC supply
25	CLK	Serial Clock
26	SID	Serial Data In
27	LE	Latch Enable
Backside Paddle	RF/DC Ground	RF/DC ground. Provide recommended via pattern (see page 8) and ensure good solder attach for best thermal and electrical performance.

PC Board Specifications

PCB Material (stackup):

- 1/2oz. Cu top layer
- 0.014 inch Nelco N-4000-13 ($\epsilon_r=3.7$ typ.)
- 1/2oz. Cu middle layer 1
- Core Nelco N-4000-13
- 1/2 Cu middle layer 2
- 0.014 inch Nelco N-4000-13
- 1/2oz. Cu bottom layer

Finished board thickness is 0.062±.006 inches

The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

